

Automotive Electronics Council

Component Technical Committee

Agenda

(subject to change)

**2026 - Twenty-Fifth Annual
Automotive Electronics
Reliability Workshop**

March 31 - April 2

**Novi, MI
Sheraton Detroit Novi Hotel**

Tuesday, March 31, 2026

7:30 AM - 8:15 AM

Continental Breakfast (provided)

8:15 AM - 9:00 AM

Workshop Opening & Chairman's Report (Mike Buzinski AEC Chair)

Session 1: Passive Components - Technology Improvements 9:00 AM - 10:00 AM Moderator: Saad Lambaz	1.1	9:00 AM - 9:30 AM	Patrick Brandt <i>John Deere</i>	AEC Q200 Case Study
	1.2	9:30 AM - 10:00 AM	Allan Webber / Mark Yampolsky <i>Texas Instruments</i>	Qualifying Semiconductor-Based Passive Components for Emerging Automotive Applications: A Comparative Analysis of AEC Standards

10:00 AM - 10:30 AM

BREAK: Coffee, drinks (provided)

Session 1: (continued) Passive Components - Technology Improvements 10:30 AM - 11:30 AM Moderator: Saad Lambaz	1.3	10:30 AM - 11:00 AM	Alan Cooper / Christoph Raible <i>Yageo/TDK</i>	AEC-Q200: New Requirements for Mission Profiles (MP) for Electric Vehicles (EV) - A Proposal for a Method to Assess the Requirements
	W.1	11:00 AM - 11:30 AM	AEC-Q200 Activity Status & Discussion <i>Moderator: Saad Lambaz, Littelfuse & AEC Q200 Task Group</i>	

11:30 AM - 1:00 PM

LUNCH (on own)

Session 2: Workshop Discussions (Discrete, WBG, Cu-Wire and Opto) 1:00PM - 2:30 Moderator: Mike Buzinski	W.2	1:00 PM - 1:15 PM	AEC-Q101 Activity Status & Discussion <i>Moderator: Mike Buzinski, Microchip</i>	
	W.3	1:15 PM - 2:15 PM	Wide Band Gap Activity Status & Discussion <i>Moderator: Joe Butcher, Nexperia & WBG Task Group</i>	
	W.4	2:15 PM - 2:30 PM	AEC-Q006 Activity Status & Discussion <i>Moderator: Rene Rongen, NXP & AEC Q006 Task Group</i>	
	W.5	2:30 PM - 3:00 PM	AEC-Q102 Activity Status & Discussion <i>Moderator: Mike Buzinski, Microchip</i>	

3:00 PM - 3:30 PM

BREAK: coffee, drinks, snacks (provided)

Session 3: Workshop Discussions Q103 / Q105 3:30 PM - 5:00 PM Moderator: Mike Buzinski	W.6	3:30 PM - 3:45 PM	AEC-Q103-001 MEMs accelerometer - History and Status <i>Moderator: Mike Buzinski, Microchip</i>	
	W.7	3:45 PM - 4:00 PM	AEC-Q103-002 MEMs pressure - Status & Discussion AEC-Q103-003 MEMs microphone - Status & Discussion <i>Moderator: Bassel Atala, ST</i>	
	W.8	4:00 PM - 4:30 PM	AEC-Q105 LCD Displays Activity Status & Discussion <i>Moderator: Steve Sibrel, Harman</i>	

4:30 PM

SESSION CLOSE

RECEPTION

5:00 PM - 6:00 PM

Mackinac Room - Hosted by AEC Technical Committee (hors d'oeuvres, beer, wine, soft drinks)

Wednesday, April 1, 2026

7:30 AM - 8:00 AM

Continental Breakfast (provided)

<p align="center">Session 4: Integrated Circuits (Q100) 8:00 AM - 10:00 AM Moderator: Steve Sibrel</p>	W.9	8:00 AM - 9:00 AM	<p>AEC-Q100 Activity Status & Discussion (Including sub-specs) <i>Moderator: Ulrich Abelein, Infineon & Q100 Task Group</i></p>	
	W.10	9:00 AM - 9:30 AM	<p>AEC-Q100-005 Status & Discussion <i>Moderator: Sumit Tayal, Micron</i></p>	
	W.11	9:30 AM - 9:45 AM	<p>AEC-Q100-CDC Review & Feedback <i>Moderator: Mike Buzinski, Microchip</i></p>	
	W.12	9:45 AM - 10:00 AM	<p>AEC-Q104-QTP Review & Feedback <i>Moderator: Mellisa Uribe, Micron</i></p>	

10:00 AM - 10:30 AM

BREAK: Coffee, drinks, snacks (provided)

<p align="center">Session 5: Q104 and FA 10:30 AM - 11:30 AM Moderator: Mike Buzinski</p>	W.13	10:30 AM - 11:00 AM	<p>AEC-Q104 Multi-Chip Modules Activity Status & Discussion <i>Moderator: Steve Sibrel, Harman</i></p>	
	4.1	11:00 AM - 11:30 AM	John Grogan Macronix	Challenges to Failure Analysis for Secure Flash Memory Chip

11:30 AM - 1:00 PM

LUNCH (on own)

<p align="center">Session 6: Zero Defect Methodologies 1:00 PM - 2:30 PM Moderator: Rene Rongen</p>	6.1	1:00 PM - 1:30 PM	Horst Lewitschnig <i>Infineon</i>	Reliability First - From the Bathtub Curve to Design for Stress
	6.2	1:30 PM - 2:00 PM	Jimmy He / Craig Hillman <i>Synopsys</i>	Compact IP Protected Models for Electronics Reliability Supply Chain
	6.3	2:00 PM - 2:30 PM	Gary Capron <i>Micron</i>	Automating the Control Plan from the PFMEA

2:30 PM - 3:00 PM

BREAK: Coffee, drinks, snacks (provided)

<p align="center">Session 6 (Continued): Zero Defects Methodologies 3:00 PM - 5:00 PM Moderator: Rene Rongen</p>	6.4	3:00 PM - 3:30 PM	David Price <i>KLA</i>	HVM "Golden Recipe" Methodology for SiC Substrate Qualification Across Suppliers, Part 2
	6.5	3:30 PM - 4:00 PM	Jimmy He / Adarsh Chaurasia <i>Synopsys</i>	Using Superelement Model in Active Thermal Cycle with Temperature Dependent Properties
	W.14	4:00 PM - 4:30 PM	<p>AEC-Q004-001 Zero Defects Casebook Review & Discussion <i>Moderator: Rene Rongen, NXP Semiconductors & AEC Q004 Task Group</i></p>	
			<p align="center">OPEN DISCUSSION AS TIME ALLOWS</p>	

5:00 PM

SESSION CLOSE

Thursday, April 2, 2026

7:30 AM - 8:00 AM

Continental Breakfast (provided)

Session 7: Systems and Mission Profiles 8:00 AM - 9:30 AM Moderator: Mike Buzinski	7.1	8:00 AM - 8:30 AM	Greg Osullivan <i>Micron</i>	Test Method for ESD Evaluation of an Electronic Module Edge Connector Performance
	W15	8:30 AM - 9:00 AM	AEC-Q007 BLR - Review & Feedback <i>Moderator: Steve Sibrel, Harman & Q007 Task Group</i>	
	W16	9:00 AM - 10:00 AM	(Extended Mission Profiles) Committee Status <i>Moderator: Rene Rongen</i>	
		10:00 AM - 10:30 AM	BREAK: Coffee, drinks, snacks (provided)	
Session 8: Misc. Topics 10:00 AM - 12:00 PM Moderator: Mike Buzinski		10:30 AM - 11:00 AM	AEC External Cooperation <i>Moderator: Rene Rongen, NXP</i>	
		11:00 AM - 11:30 AM	OPEN DISCUSSION <i>Moderator: Mike Buzinski, Microchip</i>	
		11:30 AM - 11:45 AM	AEC Asia Workshop - Coming this October! <i>Moderator: Rene Rongen, NXP, Dave Tan, iST</i>	
WRAP-UP		11:45 PM - 12:00 PM	AEC Technical Committee	Closing Statements & Workshop Adjourned